

## AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application.

1. (Original) An apparatus comprising:  
a metal deposition tool having annealing capability.
2. (Original) The apparatus of claim 1 further comprising an annealing chamber on said metal deposition tool.
3. (Original) The apparatus of claim 2 wherein said metal deposition tool is an electroplating tool.
4. (Original) The apparatus of claim 2 wherein said metal deposition tool is a chemical vapor deposition (CVD) tool .
5. (Original) The apparatus of claim 1 wherein said metal deposition tool has a plurality of metal deposition chambers, said metal deposition tool being modified to replace one of said metal deposition chambers with an annealing chamber. .
6. (Original) The apparatus of claim 5 wherein said metal deposition tool is an electroplating tool and said metal deposition chamber is an electroplating chamber.

7. (Original) The apparatus of claim 5 wherein said metal deposition tool is a chemical vapor deposition (CVD) tool and said metal deposition chamber is a chemical vapor deposition (CVD) chamber.
8. (Original) The apparatus of claim 1 wherein said metal deposition tool includes at least one metal deposition chamber and an annealing chamber on said metal deposition tool.
9. (Original) The apparatus of claim 8 wherein said metal deposition tool is an electroplating tool and said metal deposition chamber is an electroplating chamber.
10. (Original) The apparatus of claim 8 wherein said metal deposition tool is a chemical vapor deposition (CVD) tool and said metal deposition chamber is a chemical vapor deposition (CVD) chamber.
11. (Original) The apparatus of claim 8 wherein said annealing chamber includes heat lamps.
12. (Original) The apparatus of claim 8 wherein said annealing chamber is a furnace.
13. (Original) The apparatus of claim 8 further comprising a robot, wherein said robot moves a wafer from said metal deposition chamber to said annealing chamber.
14. (Original) An apparatus comprising:  
an chemical mechanical polishing (CMP) tool having annealing capability.

15. (Original) The apparatus of claim 14 further comprising an annealing chamber on said CMP tool.
16. (Original) The apparatus of claim 14 wherein said CMP tool has a plurality of CMP platforms, said CMP tool being modified to replace one of said CMP platforms with an annealing chamber.
17. (Original) The apparatus of claim 14 wherein said CMP tool includes at least one CMP platform and an annealing chamber on said CMP tool.
18. (Original) The apparatus of claim 14 wherein said annealing chamber includes heat lamps.
19. (Original) The apparatus of claim 14 wherein said annealing chamber is a furnace.
20. (Original) The apparatus of claim 14 further comprising a robot, wherein said robot moves a wafer from said annealing chamber to said CMP platform.
21. – 30. (Cancelled)